



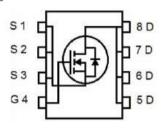
MJ N-Channel Super Trench II Power MOSFET

Description

The series of devices uses Super Trench II technology that is uniquely optimized to provide the most efficient high frequency switching performance. Both conduction and switching power losses are minimized due to an extremely low combination of $R_{DS(ON)}$ and Q_g . This device is ideal for high-frequency switching and synchronous rectification.

General Features

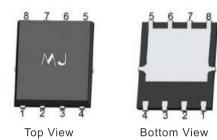
- ◆ Excellent gate charge x R_{DS(on)} product(FOM)
- ◆ Very low on-resistance R_{DS(on)}
- ◆ 150°C operating temperature
- ◆ Pb-free lead plating



Schematic Diagram

Application

- ◆ DC/DC Converter
- ◆ Ideal for high-frequency switching and synchronous rectification



DFN 5X6

100% UIS TESTED! 100% ΔVds TESTED!

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
P065N12AGU	MJXP065N12AGU	DFN5X6-8L	-	_	-

Absolute Maximum Ratings (Tc=25℃ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	VDS	120	V
Gate-Source Voltage	Vgs	±20	V
Drain Current-Continuous	lo	90	А
Drain Current-Continuous(Tc =100°C)	I D(100℃)	64	А
Pulsed Drain Current (Note 1)	Ірм	360	А
Maximum Power Dissipation	Po	130	W
Derating factor		1.04	W/°C
Single pulse avalanche energy (Note 4)	Eas	400	mJ
Operating Junction and Storage Temperature Range	Тл,Тѕтс	-55 To 150	°C

Thermal Characteristic

Thermal Resistance, Junction-to-Case	Rөjc	0.96	°C/W
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Electrical Characteristics (Tc=25℃ unless otherwise noted)

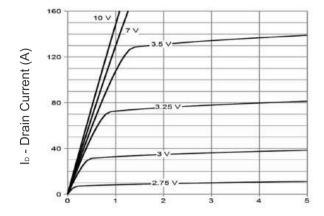
Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics			1			
Drain-Source Breakdown Voltage	BVDSS	V _{GS} =0V I _D =250µA	120	_	-	V
Zero Gate Voltage Drain Current	loss	V _{DS} =120V,V _{GS} =0V	-	-	1	μA
Gate-Body Leakage Current	lgss	V _{DS} =±20V,V _{DS} =0V	-	-	±100	nA
On Characteristics (Note 3)	,					
Gate Threshold Voltage	VGS(th)	V _{DS} =V _{GS} ,I _D =250µA	1.2	1.8	2.5	V
		V _{GS} =10V,I _D =45A	-	5.6	6.5	mΩ
Drain-Source On-State Resistance	RDS(ON)	V _{GS} =4.5V,I _D =45A	-	6.9	7.8	mΩ
Forward Transconductance	grs	V _{DS} =5V,I _D =45A	_	60	-	S
Dynamic Characteristics (Note 3)			ı	1		
Input Capacitance	Clss		_	4900	-	PF
Output Capacitance	Coss	V _{DS} =60V,V _{GS} =0V F=1.0MHz	-	300	_	PF
Reverse Transfer Capacitance	Crss		_	34	_	PF
Switching Characteristics (Note 3)			ı			1
Turn-on Delay Time	t _{d(on)}		-	20	-	nS
Turn-on Rise Time	tr	VDD=60V,ID=45A	_	15	-	nS
Turn-Off Delay Time	t _{d(off)}	V _{BS} =10V,R _G =1.6Ω	_	40	_	nS
Turn-Off Fall Time	tr	- 10		-	nS	
Total Gate Charge	Qg		-	90	-	nC
Gate-Source Charge	Qgs	V _{DS} =60V,I _D =45A V _{GS} =10V	-	21	_	nC
Gate-Drain Charge	Qgd	V 66 10 V	-	23.5	_	nC
Drain-Source Diode Characteristics						1
Diode Forward Voltage (Note 2)	Vsp	V _{GS} =0V,I _S =45A	-	-	1.2	V
Diode Forward Current	ls		-	_	90	Α
Reverse Recovery Time	trr		_	70	_	nS
Reverse Recovery Charge	Qrr	TJ=25°C,IF=45A di/dt= 100A/µs (Note 3)		137		nC

Notes:

- $\textcircled{1} \ \mathsf{Repetitive} \ \mathsf{Rating:} \ \mathsf{Pulse} \ \mathsf{width} \ \mathsf{limited} \ \mathsf{by} \ \mathsf{maximum} \ \mathsf{junction} \ \mathsf{temperature}.$
- ② Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2%.
- 3 Guaranteed by design, not subject to production
- 4 EAS condition : Tj=25°C,VDD=50V,VG=10V,L=0.25mH,Rg=25 Ω

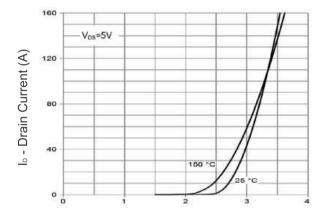


Typical Electrical and Thermal Characteristics



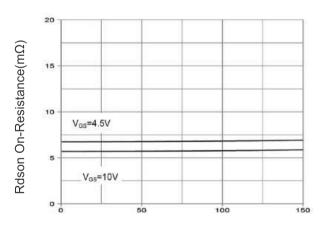
Vds Drain-Source Voltage (V)

Figure 1 Output Characteristics



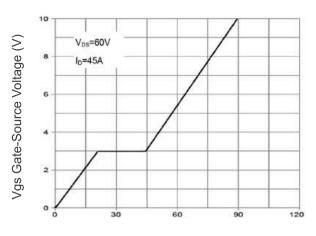
Vgs Gate-Source Voltage (V)

Figure 2 Transfer Characteristics



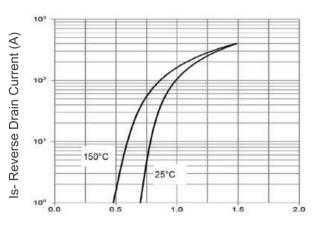
l₀ - Drain Current (A)

Figure 3 Rdson- Drain Current



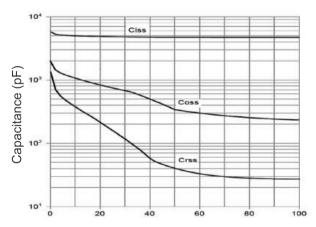
Qg Gate Charge (nC)

Figure 4 Gate Charge



Vsd Source-Drain Voltage (V)

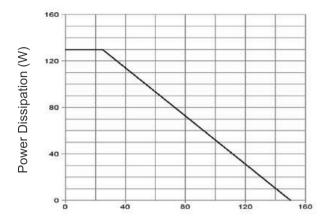
Figure 5 Source- Drain Diode Forward



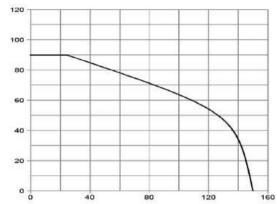
Vds Drain-Source Voltage (V)

Figure 6 Capacitance vs Vds





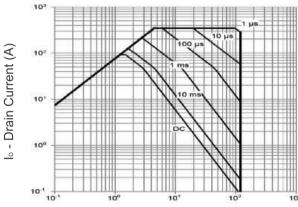
I_D - Drain Current (A)



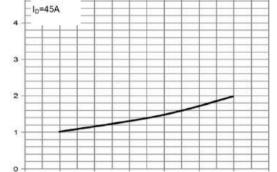
T_J-Junction Temperature(°C)

Figure 7 Power De-rating

T_J-Junction Temperature(°C) Figure 9 Current De-rating







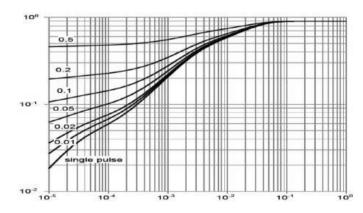
Vds Drain-Source Voltage (V)

Figure 8 Safe Operation Area

T_J-Junction Temperature(°C)

Figure 10 Rdson-Junction Temperature





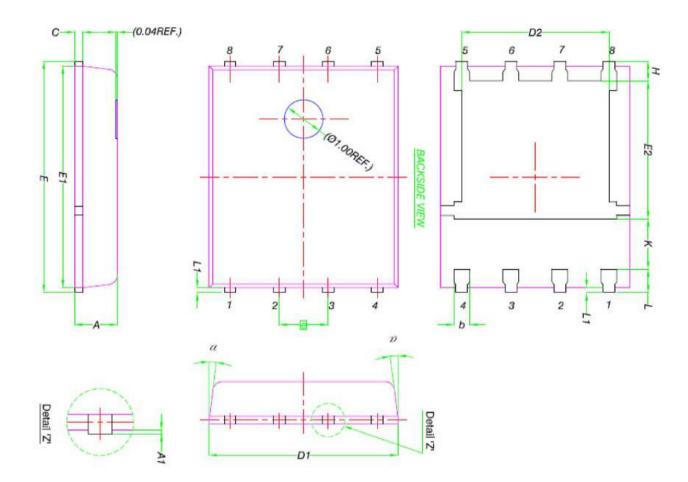
Square Wave Pluse Duration(sec)

Figure 11 Normalized Maximum Transient Thermal Impedance

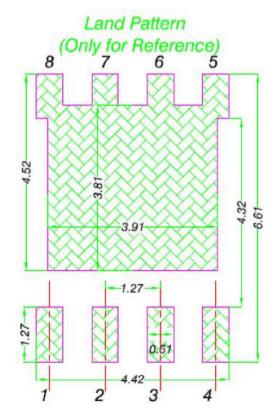




DFN5X6-8L Package Information



DIM.	MILLIMETERS				
	MIN.	NOM.	MAX.		
Α	0.90	1.00	1.10		
A1	0		0.05		
b	0.33	0.41	0.51		
C	0.20	0.25	0.30		
D1	4.80	4.90	5.00		
D2	3.61	3.81	3.96		
Ε	5.90	6.00	6.10		
E1	5.70	5.75	5.80		
E2	3.38	3.58	3.78		
е	1.27 BSC				
Н	0.41	0.51	0.61		
K	1.10	+	**		
L	0.51	0.61	0.71		
L1	0.06	0.13	0.20		
α	O°	-	12°		





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